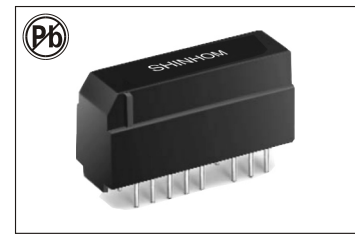


ISDN S-INTERFACE MAGNETICS MODULES

HS5011-5015



FEATURES:

- Meet Industry Standard Footprints.
- Designed for enhanced EMC performance.
- ISDN Interface Isolation
- Through-Hole Dual 1500Vrms

OPTIONS:

- Bulk Packaging is Standard
- Custom Design Available

COMMON APPLICATIONS:

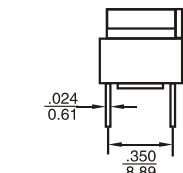
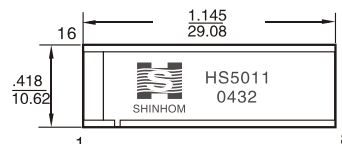
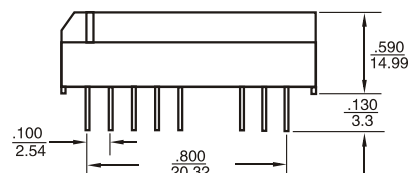
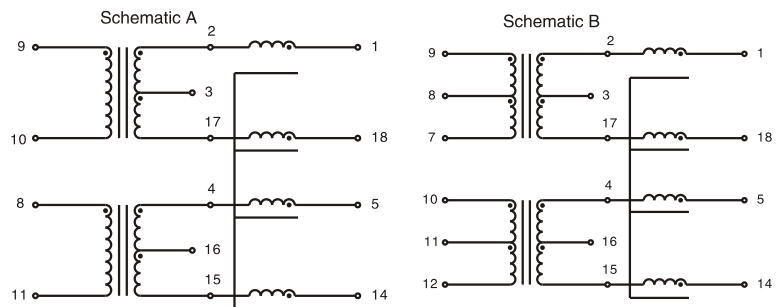
- Cable interface for isolation and low common mode emissions.
- Designed to fit behind 1x1 RJ45 connector.
- ISDN S-Interface Single Port

STANDARD SPECIFICATIONS

Part Number	Transformer						Choke				Schematic
	Inductance OCL (mH min)	Inductance Leakage (μ H max)	Interwinding Capacitance (pF max)	DC Resistance (Ω Max)		Turn Ratio Pri: Sec (± 3%)	Inductance OCL (mH min)	Inductance Leakage (μ H max)	DC Resistance (Ω Max)	Turn (± 5%)	
				Pri	Sec						
HS5011	30	10	150	4.00	4.0	1CT:1CT	4.70	0.6	1.20	1:1:1	A
HS5012	30	30	150	4.00	6	1CT:2CT	4.70	0.6	1.20	1:1:1	A
HS5013	30	30	150	4.00	9	1CT:2.5CT	4.70	0.6	1.20	1:1:1	A
HS5015	30	30	150	4.00	6	1CT:2CT	4.70	0.6	1.20	1:1:1	B

TECHNICAL INFORMATION & PHYSICAL CHARACTERISTICS:

- Dimmension: Inch/mm
 - Isolation Hi-pot: 1500Vrms(pri/sec)
 - Soldering methods:Wave,Reflow
 - Operating Temperature:0°C to 70°C
 - Storage Temperature:-55°C to 125°C
- Note:All specifications subject to change without notice.



Recommended Pad Layout

